

UI **UI Science Profile**
Equipment for next generation

UI SCIENCE Co.,ltd.

Profile of UI SCIENCE

○Head office UI SCIENCE Co., Ltd.

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○Company Profile

Established	September 2016
Capital	100,000,000Jpy
Main bank	Chiba bank、Keiyo bank
Representative	
Director and President	Shinichi Umemoto
Sales results 2023	1,300,000,000Jpy
Sales record	17 equipment

○Sales equipment type

RtoR Connector Plating Equipment
Full Auto Wafer Plating System
Semi Auto Wafer Plating System
Lead frame Plating Equipment Cut Sheet or RtoR
PCB Plating Equipment、
Plating Tool (Silicon mask etc)



Introduction of UI SCIENCE

Confidential

Concept of Equipment

- **We are familiar with the latest plating equipment technology.
State-of-the-art equipment group.**
- **Our equipment was designed for high spec ideas.
This is a custom-made Equipment for which you can request specifications.**

Organizational Structure

Officer Sales

Accounting, general affairs

Technical design

Production control

Production

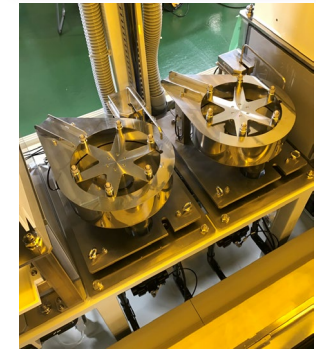
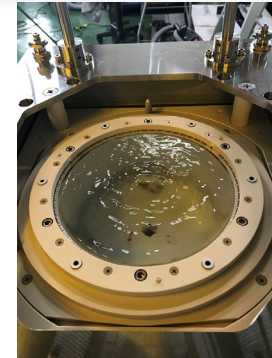
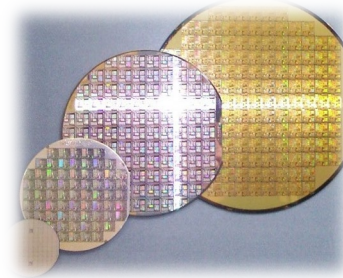
System Control

Introduction of Plating equipment.

Confidential

Full Auto Wafer Plating System

Model	: FAWPS-04~08
Chamber	: 4~8 Chamber
Through put	: MAX 10000wafer/month
Wafer size	: ϕ 75- ϕ 100- ϕ 125- ϕ 150- ϕ 200 3inch-4inch-5inch-6inch-8inch
Plating spec	: Cu, NI, Au, Sn etc
Wafer material	: Silicon Wafer /GaAs Wafer GaN Wafer etc



○Concept of system

- Equipped with SCARA robot for stable transportation and high quality plating .
- The two-handed SCARA robot does not stain the wafer.
- Production recipe, production record, production recording function installed (compliant with SECS standard)
- High quality plating supported by original face down Chamber
- Supports high-quality plating by installing wafer contact ring cleaning function



(Model 2023 ϕ 200-8chamber-4SRD)

Introduction of Plating equipment.

Confidential

Semi Auto Wafer Plating System

- Model : SAWPS-04~14
- Chamber : 4~14 Chamber
- Through put : MAX 10000wafer/month
- Wafer size : ϕ 75- ϕ 100- ϕ 125- ϕ 150- ϕ 200
3inch-4inch-5inch-6inch-8inch
- Plating spec : Cu、NI、Au、Sn etc
- Wafer material : Silicon Wafer /GaAs Wafer
GaN Wafer etc

Φ 200 8inch Cu 4+4+2



Φ 200 8inch Cu 8+6

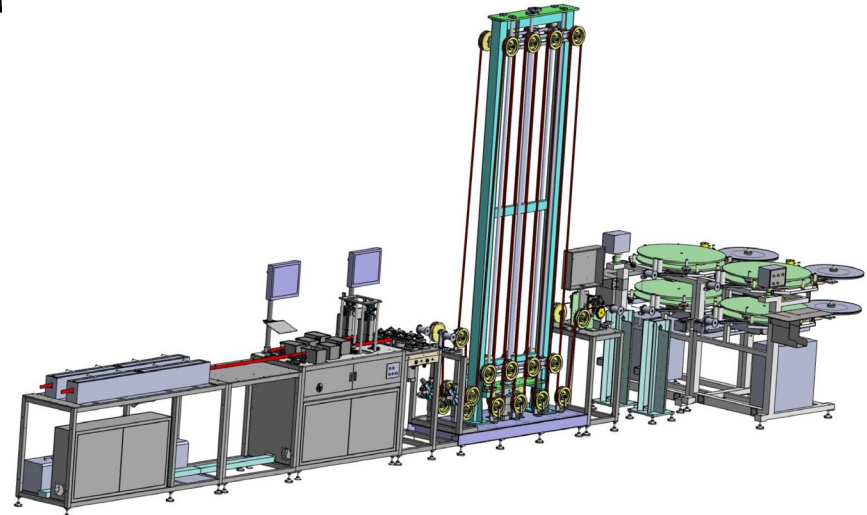


Introduction of Plating equipment.

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RtoR Connector Plating Equipment

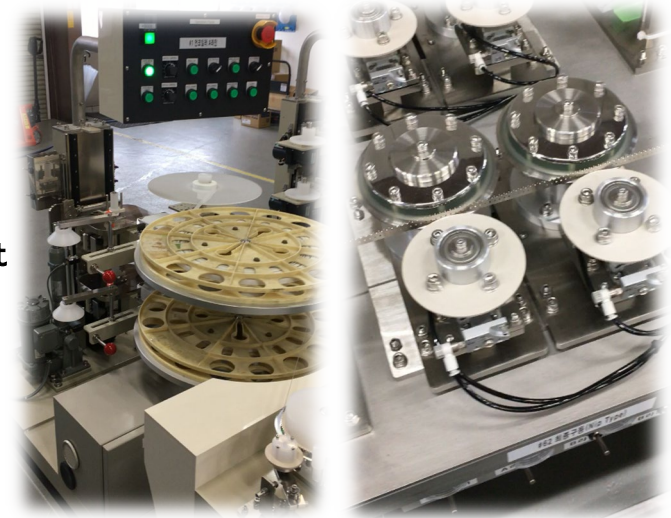
Model : UIRC-01 ~04
Number of line : 1line~4line (MAX4line)
Drive speed : 1.0~25.0m/min
Production item : Connector、Foop
: Thickness t0.06~t1.0mm
: Hight 5~120mm



Basic plating spec :Ni+Pd+Au+Sn
: Cu+Sn+Reflow etc
Material : Cu、SUS etc

○Concept of Equipment

- narrow-pitch micro connector products and high quality plating support
- Automotive connector products and high quality plating support
- High-precision partial plating is possible by processing various parts plating tool



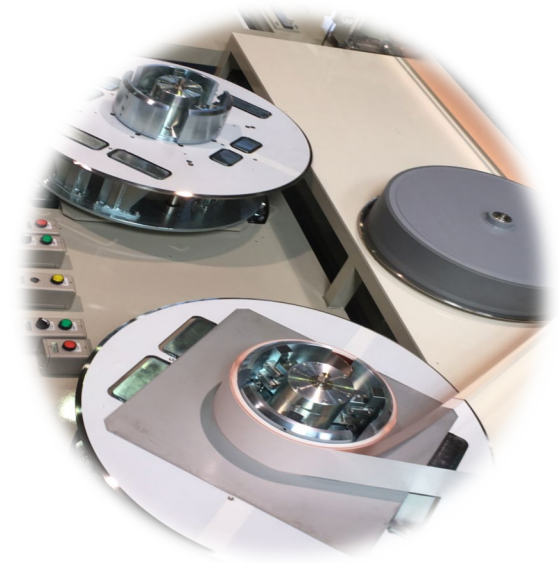
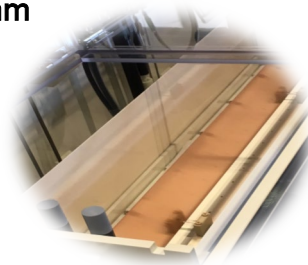
Introduction of Plating equipment.

Confidential

Lead frame Plating Equipment

RtoR type plating equipment

Model : UIRLF-02 ~04
Number of line : 1line~4line (MAX4line)
Drive speed : 1.0~5.0m/min
Production item : Lead frame、Foop
: Thickness t0.06~t1.0mm
: Hight 5~120mm
Basic plating spec :Ni+Pd+Au
: Cu+Ag etc
Material : Cu、SUS etc



○Concept of Equipment

- High-precision partial plating is possible by processing various parts plating tool
- Spot plating position accuracy ± 0.07 mm achieved

Introduction of Plating equipment.

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Lead frame Plating Equipment

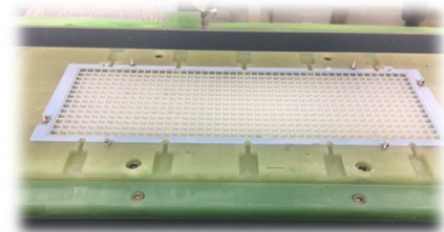
Cut sheet type plating equipment

Model : UICLF-02 ~04
Number of line : 1line~4line (MAX4line)
Conveyer speed : 1.0~2.0m/min
Production item : Lead frame cut sheet
: Thickness t0.06~t0.8mm
: Wide 50~100mm
Basic plating spec :Ni+Pd+Au
: Cu+Ag etc
Material : Cu , SUS etc



○Concept of Equipment

- High-precision partial plating is possible by processing various parts plating tool
- Spot plating position accuracy ± 0.05 mm achieved



Introduction of control system (A D L S)

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Auto Data Logging System

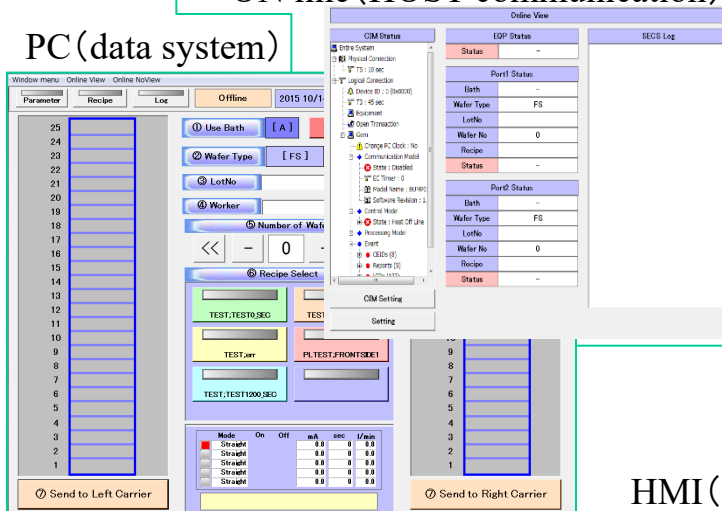
- Equipment control (Drive, robot control, etc.)
- Recipe D/L, data collection, alarm history management (PC control)
- Recipe U/L, host communication management (online control)



User HOST server
SECS/GEM

ON line (HOST communication)

PC (data system)



PLC (system Control)

PLC (system Control)



Melsecnet/H

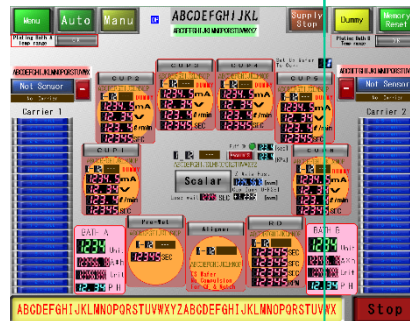


M/C Control

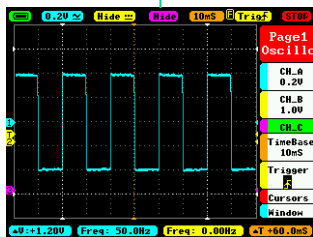
Ethernet

CC-Link
FAcom

HMI (system Control)



Ethernet



RS-232C communication

Ethernet

Inspection Control

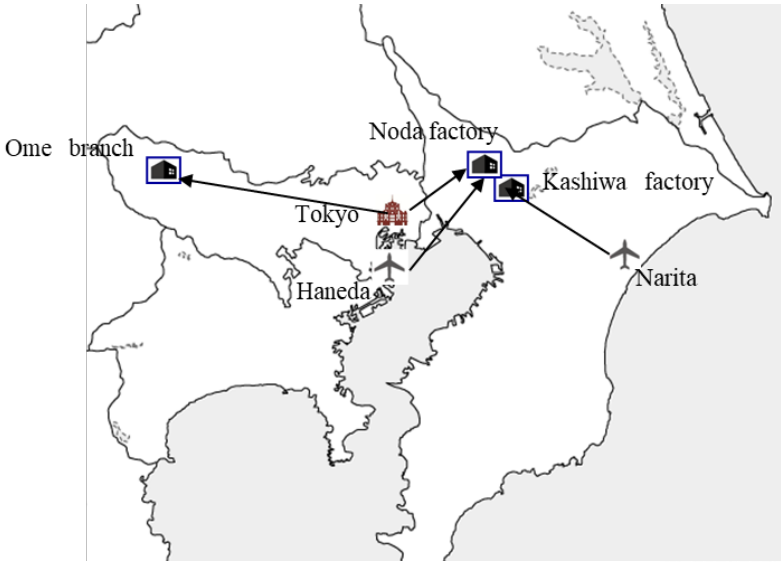
In line record



Access to UI SCIENCE

Always access to the station

- 35 minutes by train from Tokyo Station
- 60 minutes by train from Haneda Airport
- 75 minutes by bus
- 60 minutes by train from Narita Airport
- 90 minutes by bus



- Head office factory** 12m × 25m
- Second factory** 15m × 31m
- Tokyo branch** 12m × 25m

